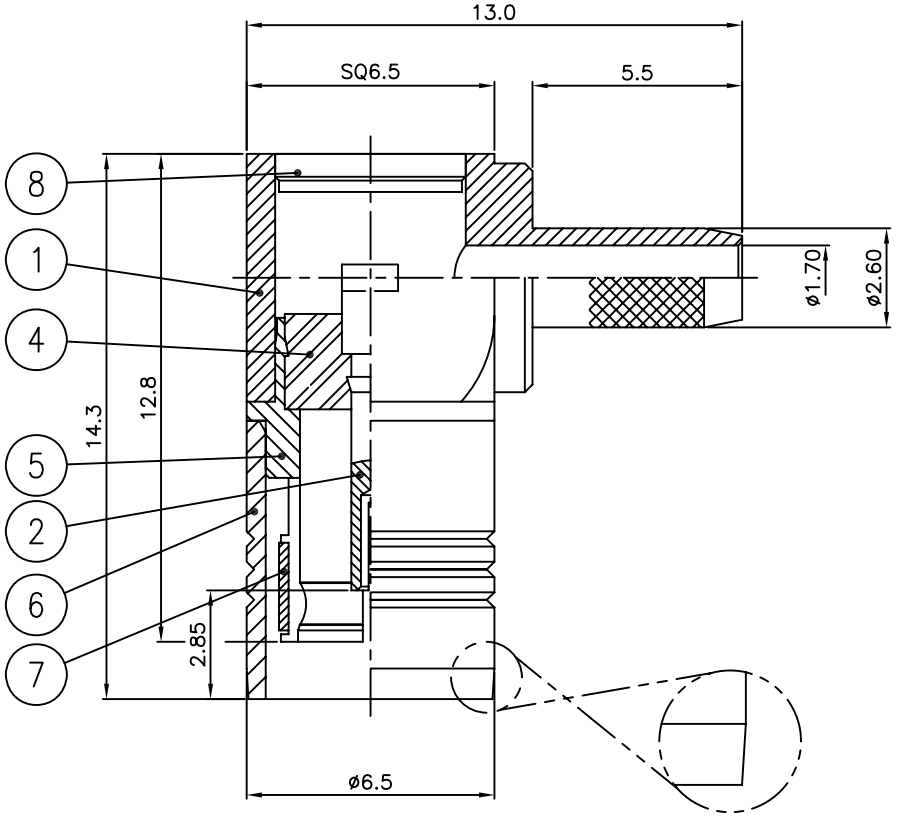
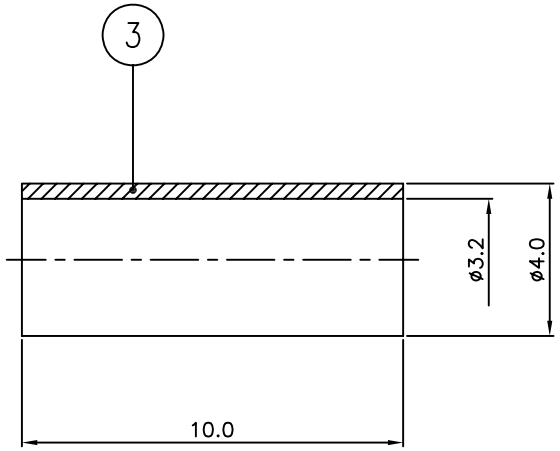
REVISION				
REV	DESCRIPTION	DRAWN	APPR	DATE
IR	Initial Registration	E.H.KIM	I.C.KIM	2013.11.04.
1	[설변No.201608-0006] 가공 업체 공구에 맞춰 BODY, JACK, COVER 치수 변경	H.J.LEE	I.C.KIM	2016.08.12.
2	[설변No.202201-0007] 조립공차 변경 및 CAP 조립방향 확대도 추가	S.Y.EUN	I.C.KIM	2022.01.17.
3	[설변No.202201-0008] COVER 조립 시 Burr 개선으로 인한 코드 변경	S.Y.EUN	I.C.KIM	2022.01.17.





* CAP 조립 시 면취 방향 확인 후 조립할 것
(조립 방향 주의) 2

	NO.	DESCRIPTION	Q'TY	MATERIAL	PLATING	CODE
3 1	8	COVER	1	MBsBD C3604BD-F	Gold Plate	DCO00096-5/3 ~~DCO00115-5/1~~ ~~DCO00083-5/1~~
	7	SPRING RING	1	BeCu C17300	Copper Plate	DSR00009-5/1
	6	CAP	1	MBsBD C3604BD-F	Gold Plate	DCU02202-5/1
1	5	JACK	1	MBsBD C3604BD-F	Gold Plate	DJA00168-5/1
	4	INSULATOR	1	TEFLON		DIN02132-N/1
	3	FERRULE	1	MBsBD C3604BD-F	Nickel Plate	DFE00034-5/1
	2	CONTACT	1	BeCu C17300	Gold Plate	DCT02760-5/1
1	1	BODY	1	MBsBD C3604BD-F	Gold Plate	DBD03478-5/1

2 TOLERANCE	Decimal ±0.2 ~~±0.1~~	DATE	2022. 01. 17.
	Angle ±1°	APPROVED BY	S.H.KIM
		CHECKED BY	
MATERIAL		DRAWN BY	S.Y.EUN
FINISH		SCALE 5/1	UNIT mm

KJ COMTECH
KJ COMTECH CO.,LTD.
RF & MICROWAVE TECHNOLOGY
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TITLE
SMB75 CABLE PL RG179

A4 | DWG NO. CN02945-7/1 | REVISION 3 | SHEET 1 of 1